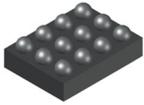
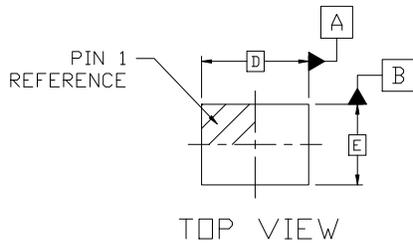


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

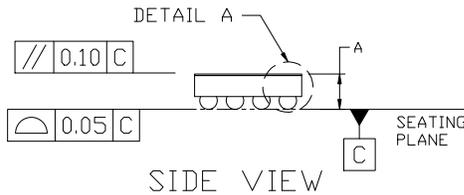


WLCSP12 1.62x1.22x0.539
CASE 499BJ
ISSUE D

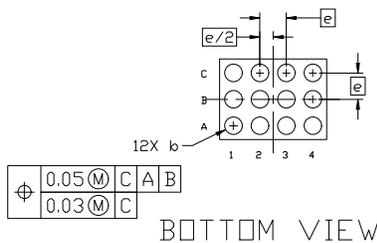
DATE 02 JUN 2022



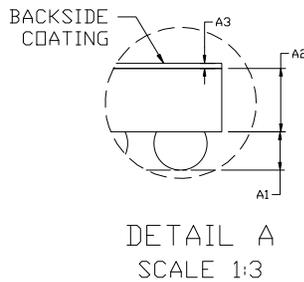
TOP VIEW



SIDE VIEW



BOTTOM VIEW

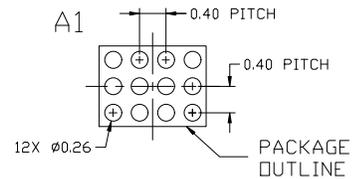


DETAIL A
SCALE 1:3

NOTES:

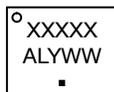
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION *b* IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.484	0.539	0.594
A1	0.164	0.194	0.224
A2	0.295	0.320	0.345
A3	0.025 BSC		
<i>b</i>	0.239	0.269	0.299
D	1.62 BSC		
E	1.22 BSC		
<i>e</i>	0.40 BSC		



RECOMMENDED
MOUNTING FOOTPRINT*

**GENERIC
MARKING DIAGRAM***



- XXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- WW = Work Week
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP12 1.62x1.22x0.539	PAGE 1 OF 1

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